CLAIMS

1. A method for manufacturing a printed wiring board, including: forming a resin layer by superposing a semi-cured resin sheet on a printed wiring board with circuit patterns formed thereon; pressing and forcing the resin layer into spaces between said circuit patterns and curing said resin layer; and then polishing said cured resin layer covering said circuit patterns, thereby exposing said circuit patterns,

wherein a resin sheet with resin patterns complementary to said circuit patterns are included on a surface of said resin sheet facing said circuit patterns before said resin sheet is superposed on said printed wiring board.

2. A method for manufacturing a printed wiring board, including: forming a resin layer by superposing a semi-cured resin sheet on a printed wiring board where through holes and circuit patterns are formed; pressing and forcing the resin layer into spaces between said circuit patterns and curing said resin layer; and then polishing the cured resin layer covering said circuit patterns, thereby exposing said circuit patterns,

wherein additional resin for filling said through holes is included at positions of said resin sheet corresponding to said through holes before the resin sheet is superposed on said printed wiring board.

3. The method for manufacturing a printed wiring board according to claim 1 or claim 2, wherein the pressing against said resin layer is performed in a reduced pressure atmosphere.

4. The method for manufacturing a printed wiring board according to one of claim 1 to claim 3 wherein a metallic foil with a roughened surface facing said resin layer is superposed and pressed on said resin layer.

5. The method for manufacturing a printed wiring board according to claim 4 wherein said metallic foil is formed with a metal of a different kind than said circuit patterns.